

## FROM AMPHENOL BACKPLANE SYSTEMS DIVISION

For over 40 years, Amphenol Backplane Systems (ABS) has been a leading manufacturer of backplane assemblies and enclosures for military and aerospace applications. ABS combines a wide range of innovative product and process technologies, advanced component manufacturing, and process control with highly focused, customer specific program management and testing at the assembly level. In addition, we provide expert design and unsurpassed applications engineering assistance at every step of the way.

Amphenol Backplane Systems production capabilities are the result of investment in new state-of-the-art equipment and software such as:

- Press-fit installation
- Through-hole soldering
- Automated hi-temp soldering
- Large-format surface mount soldering
- Aqueous cleaning
- Conformal coat (type UR and XY)
- Electrical test

For electrical testing, ABS offers Level I (bareboard), Level II (post assembly), and Level III (in-circuit) capabilities. Our industry leading large-format surface mount line with a capability of up to 29" X 60" circuits is well positioned for the largest backplanes in the industry as well as volume production of standard backplane products.

Our advanced manufacturing support software allows us to maintain our world class configuration control as well as create a state-of-the-art visual workplace to ensure we are exceeding customer expectations. Our in-house capability for environmental testing such as Environmental Stress Screening (ESS) supports the increasing customer need for product assurance. We have also expanded our manufacturing capability to include:

- Enclosure and Value-added Assembly
- High-end Cable and Flex Assemblies
- Integrated Bus Systems
- Machined Enclosures and Metal Faceplates

In support of the continued need for leading-edge technology coupled with best cost manufacturing, we have established a qualified DoD Manufacturing Licensing Agreement (MLA) approved work center at our Amphenol Nogales, Mexico campus. This site is a duplication of our Nashua, New Hampshire manufacturing capability and will meet the needs of programs looking for a low cost option, while remaining in North America.

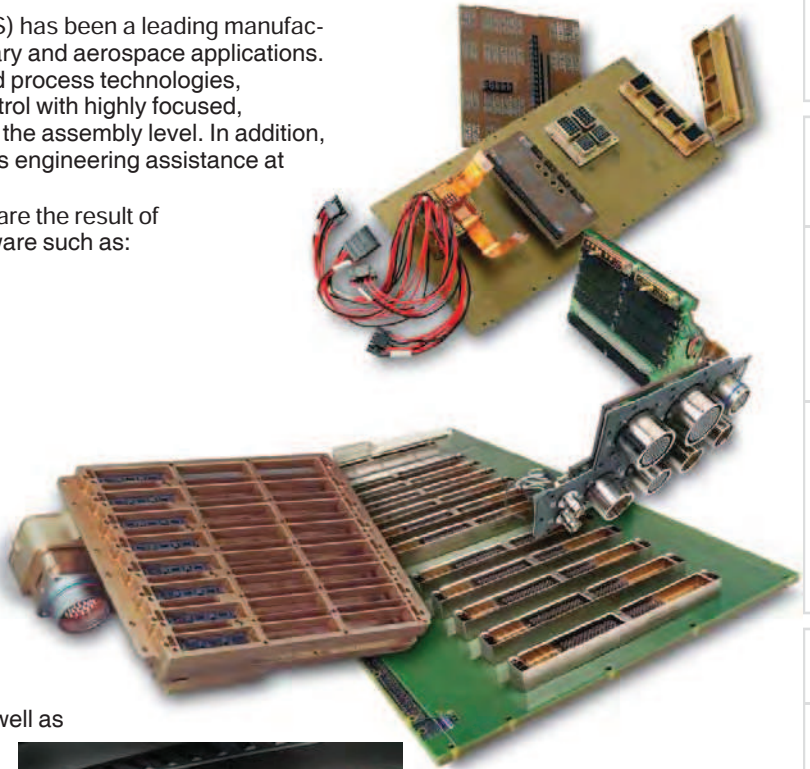
ABS MIL-Specified qualifications include MIL-C-28859 (for components) and MIL-A-28870 (for assembled backplanes).

### Amphenol's Solutions - The Pinnacle of Technology

Some of the world's most demanding programs rely on Amphenol's packaging solutions, including:

- F-35
- F-22
- F-18
- MIDS/JTRS Radio
- Theatre High Altitude Air Defense Radar (THADD)
- AH-64 Apache
- 787 Dreamliner
- Future Combat Systems
- DDG-51
- DDG-1000

Integrated Systems Solutions\* are found aboard commercial airliners, helicopters, Navy and Air Force fighters, C4I electronics, missiles, ground vehicles, Homeland Security Systems, and Navy warships.



Backplane Incorporating LRM Modules with Brush Contacts and MT Fiber Optic Inserts

Introduction/ Pkg. Solutions/ Brush Contact	LRM (Line Replaceable Modules)	High Density	Low Mating Force MIL-DTL-55302	Rack & Panel	LMD/LMS	Other
Suggested/ GEN-X	Fiber Optics/ HiSpeed/Rf/Power	HD33 HSB3 Hi Speed	Standard Brush	Brush Ruggedized	Redundant/ Interconnects	Rectangular Interconnects
Other Options/ Access-/ VME/VITA(VIPER)			Hybrid - Signal/Power/ Coax/Fiber Optics			
			Docking Conn./ Accessories/Install.			

\* See page 12 for more information about Amphenol Integrated System Solutions.